

ABSTRACT

A non-leaded type semiconductor device comprising a tab, tab suspension leads, plural leads, the tab, the tab suspension leads and the plural leads being exposed to one surface of the seal member, a semiconductor element positioned within the seal member and fixed to a surface of the tab with an adhesive, electrically conductive wires for electrically connecting electrodes on the semiconductor element and the leads with each other, and electrically conductive wires for electrically connecting the electrodes on the semiconductor element and a tab surface portion deviated from the semiconductor element with each other, wherein the tab is formed larger than the semiconductor element so that outer peripheral edges of the tab are positioned outside outer peripheral edges of the semiconductor element, a groove is formed in the tab surface portion positioned between a semiconductor element fixing area to which the semiconductor element is fixed and wire connection areas to which the wires are connected, the groove being formed so as to surround the semiconductor element fixing area, the tab has a section which is in the shape of an inverted trapezoid, and peripheral edges of the tab bite into a package. Not only the reliability of wire connection, including down bonding, is improved, but also it is possible to prevent peeling-off between the tab to

which the semiconductor element is fixed and resin which constitutes the package.